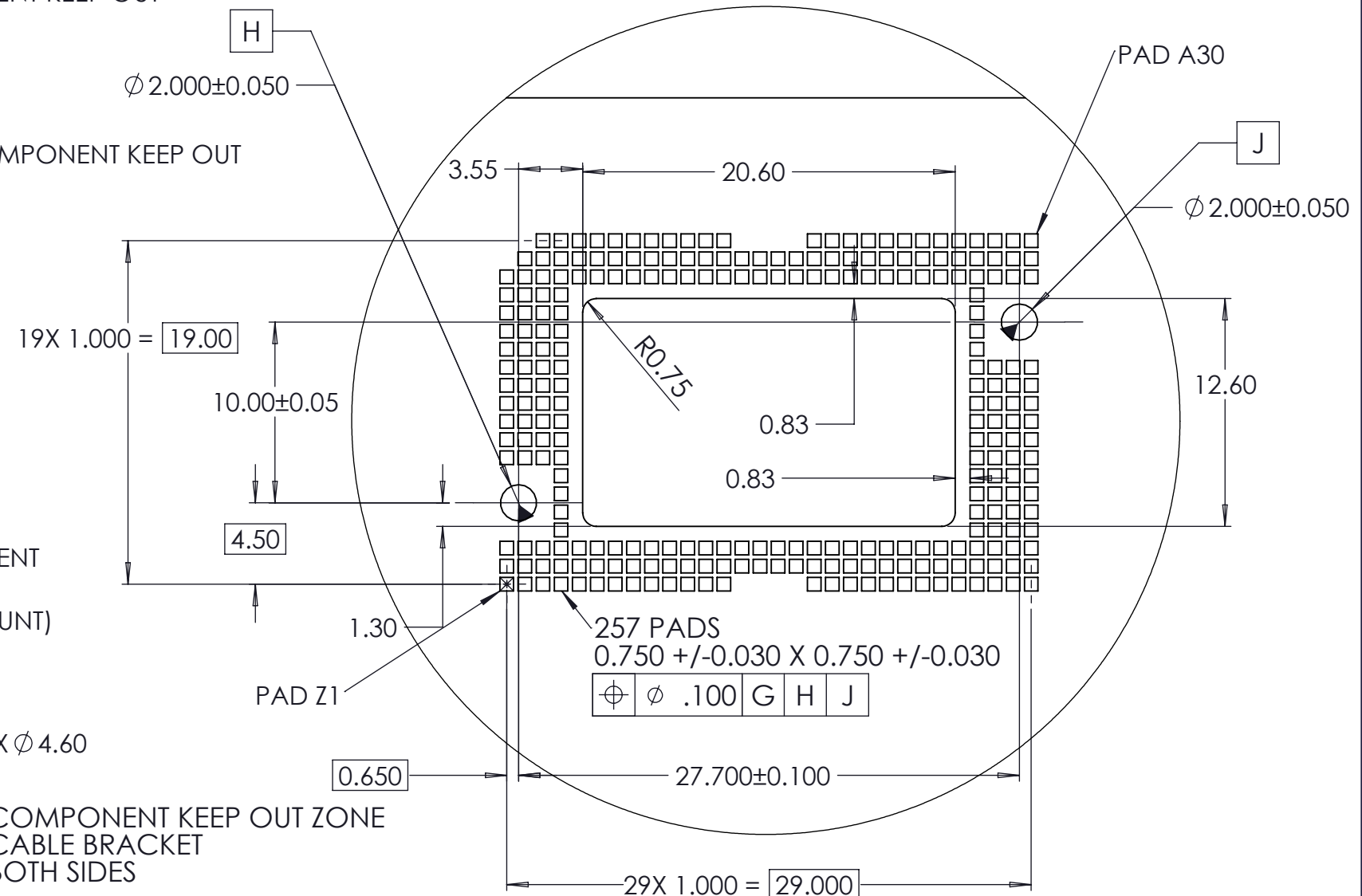


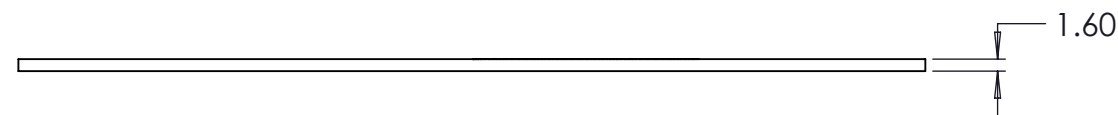
1. PLATE DMD PADS WITH A MINIMUM OF 30 MICROINCHES OF (ELECTROLYTIC) GOLD OVER 50- 100 MICROINCHES OF NICKEL
2. FILL VIAS IN PAD AREAS
3. INTERPOSER OUTLINE; NO COMPONENTS ALLOWED WITHIN THIS AREA
4. NO COMPONENTS OR SURFACE ETCH ALLOWED WITHIN THIS AREA
5. NO COMPONENTS ALLOWED WITHIN THIS AREA

DWG NO 2515279	SHEET 1	1
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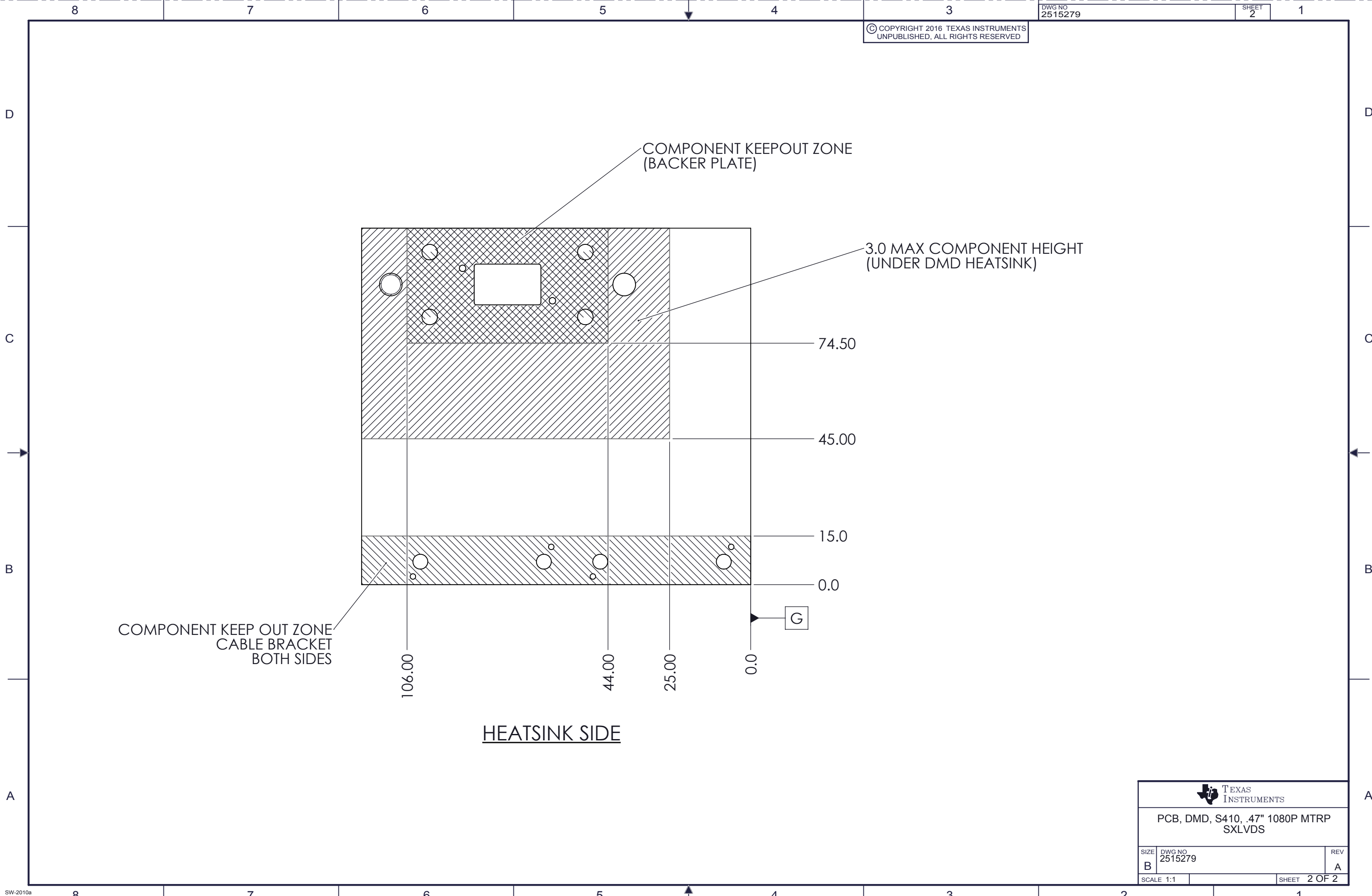
REVISIONS				
ZONE	REV.	DESCRIPTION	DATE	APPROVED
	4	RELEASE FOR ROUTING LAYOUT	08-30-16	
	A	RELEASE FOR FABRICATION MAX COMPONENT HEIGHT 3 WAS 5 : HEATSINK SIDE	09-28-16	



DETAIL A  
SCALE 3:1



		<div>UNLESS OTHERWISE SPECIFIED</div> <ul style="list-style-type: none"><li>● DIMENSIONS ARE IN MILLIMETERS</li><li>● TOLERANCES: ANGLES <math>\pm 1^\circ</math></li><li>2 PLACE DECIMALS <math>\pm 0.10</math>    3 PLACE DECIMALS <math>\pm 0.025</math></li><li>1 PLACE DECIMALS <math>\pm 0.25</math></li><li>● DIMENSIONAL LIMITS APPLY BEFORE PROCESSES</li><li>● INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994</li><li>● REMOVE ALL BURRS AND SHARP EDGES</li><li>● PARENTHETICAL INFO FOR REF ONLY</li></ul>	<div>DWN</div> <div>J. VASQUEZ</div> <div>Engr</div>	<div>DATE</div> <div>8/28/2016</div>	<div><div><div></div><div>TEXAS INSTRUMENTS</div></div></div>			<div>PCB, DMD, S410, .47" 1080P MTRP SXLVDS</div>		
			<div>COE/QA</div>							
				<div>CM</div>		<div>SIZE</div> <div>B</div>	<div>DWG NO</div> <div>2515279</div>	<div>REV</div> <div>A</div>		
				<div>Apprvd</div>		<div>SCALE</div> <div>1:1</div>		<div>SHEET</div> <div>1 OF 2</div>		
			<div>APPLICATION</div>							
		<div>NEXT ASSY</div> <div>USED ON</div>								



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DWG NO  
2515279

SHEET  
2

1



PCB, DMD, S410, .47" 1080P MTRP  
SXLVDS

SIZE  
B

DWG NO  
2515279

REV  
A

SCALE 1:1

SHEET 2 OF 2